

NOTES: UNITS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED INTERPRET THIS DRAWING IN ACCORDANCE WITH IPC-D-325A 2. BOARD FABRICATION AND QUALITY PER IPC-6012, CLASS 2, EXCEPT SPECIFIED HEREIN 3. DIMENSIONAL LIMITS APPLY AFTER PLATING OR COATING 4. STACKUP SUMMARY: A. NUMBER OF COPPER LAYERS: 4 B. BOARD THICKNESS SHALL BE: 0.20mm - 0.33mm +/- 10% (optimize for fab speed) C. COPPER: See Layer Stack D. DEFAULT TRACE/SPACE: 5mil / 5mil E. CONDUCTOR WIDTH TOLERANCE = +/- 0.01mm 5. SURFACE FINISH/PLATING: A. BOARD SHALL BE IMMERSION GOLD PLATED (ENIG) ACCORDING TO IPC-4552. THICKNESS SHALL BE A MINIMUM OF 0.05µm GOLD OVER 3-6µm NICKEL 6. SOLDERMASK WITH LIQUID PHOTO IMAGEABLE (LPI) PER IPC-SM-840C, CLASS T. COLOR: BLACK COVERLAY 7. SILKSCREEN PER SUPPLIED ARTWORK WITH ORGANIC, NON-CONDUCTIVE, EPOXY INK. SILKSCREEN MAY BE TRIMMED OFF ANY SOLDERABLE ENTITY. COLOR: WHITE 8. LOCATE MANUFACTURER'S IDENTIFICATION AND LOT CODE ON BOTTOM SIDE FREE FROM ALL METAL ENTITY RENDERED IN SILKSCREEN. 9. DETAILS NOT SPECIFIED ARE AT MANUFACTURER'S OPTION BUT FINAL APPROVAL MUST BE OBTAINED

